优尚

YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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Product Summary

BV_{DSS}	$R_{DS(ON)}$ Max	I_D Max T_A = +25°C
100V	32mΩ @ V_{GS} = 10V	6.9A
	50mΩ @ V_{GS} = 4.5V	5.8A

Features and Benefits

- 100% Unclamped Inductive Switching (UIS) Test in Production – Ensures More Reliable and Robust End Application
- Low $R_{DS(ON)}$ – Ensures On-State Losses are Minimized
- Low Input Capacitance
- Fast Switching Speed
- Wettable Flank for Improved Optical Inspection

Description and Applications

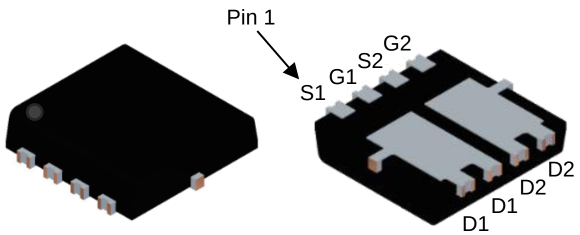
This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Wireless charging
- DC-DC converters
- Power managements

Mechanical Data

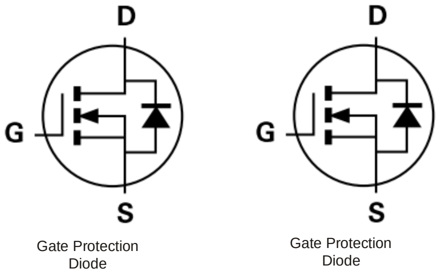
- Package: POWERDI®3333-8
- Package Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish — Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ⓔ3
- Weight: 0.03 grams (Approximate)

POWERDI®3333-8/SWP (Type UXD)



Top View

Bottom View



Internal Schematic

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	100	V
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current, V_{GS} = 10V (Note 5)	Steady State	T_A = +25°C	I_D	6.9	A
		T_A = +70°C		5.6	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I_{DM}	36	A
Maximum Continuous Body Diode Forward Current (Note 6)			I_S	2.8	A
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)			I_{SM}	36	A
Avalanche Current, L = 0.3mH			I_{AS}	13	A
Avalanche Energy, L = 0.3mH			E_{AS}	25.3	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	T_A = +25°C	P_D	1.2	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	102	°C/W
Total Power Dissipation (Note 5)	T_A = +25°C	P_D	2.8	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	45	°C/W
Thermal Resistance, Junction to Case (Note 5)		$R_{\theta JC}$	4	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	100	—	—	V	V_{GS} = 0V, I_D = 1mA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 80V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	1.3	—	2.5	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	25	32	mΩ	V_{GS} = 10V, I_D = 5A
		—	36	50	mΩ	V_{GS} = 4.5V, I_D = 5A
Diode Forward Voltage	V_{SD}	—	0.8	1.0	V	V_{GS} = 0V, I_S = 5A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	683	—	pF	V_{DS} = 50V, V_{GS} = 0V, f = 1MHz
Output Capacitance	C_{oss}	—	165	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	6.9	—	pF	
Gate Resistance	R_g	—	1.2	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = 4.5V)	Q_g	—	6.3	—	nC	V_{DS} = 50V, I_D = 6A
Total Gate Charge (V_{GS} = 10V)	Q_g	—	11.9	—	nC	
Gate-Source Charge	Q_{gs}	—	2.0	—	nC	
Gate-Drain Charge	Q_{gd}	—	3.1	—	nC	
Turn-On Delay Time	$t_{D(ON)}$	—	4.1	—	ns	V_{DS} = 50V, I_D = 5.85A V_{GS} = 10V, R_{GEN} = 3Ω
Turn-On Rise Time	t_R	—	4.5	—	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	12.5	—	ns	
Turn-Off Fall Time	t_F	—	9.3	—	ns	
Reverse Recovery Time	t_{RR}	—	31.5	—	ns	I_F = 6A, di/dt = 500A/µs
Reverse Recovery Charge	Q_{RR}	—	94.6	—	nC	

Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

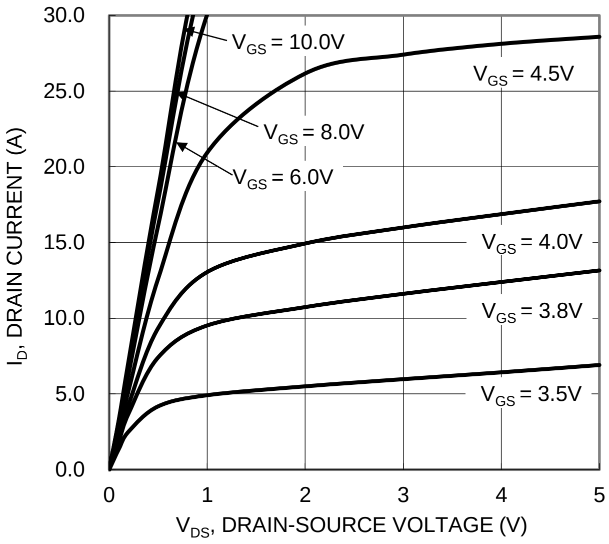


Figure 1. Typical Output Characteristic

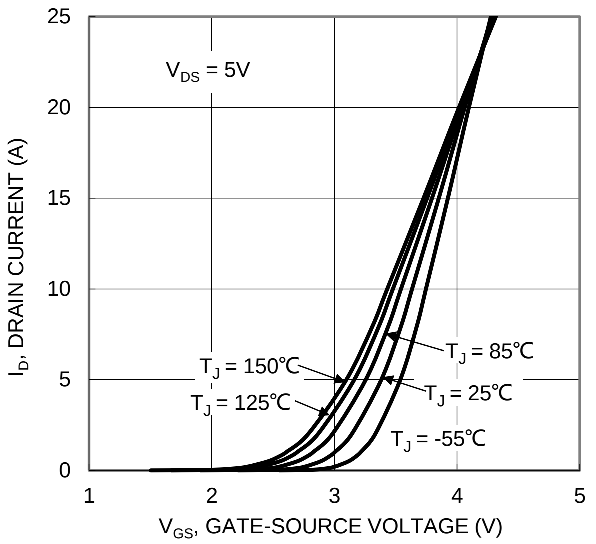


Figure 2. Typical Transfer Characteristic

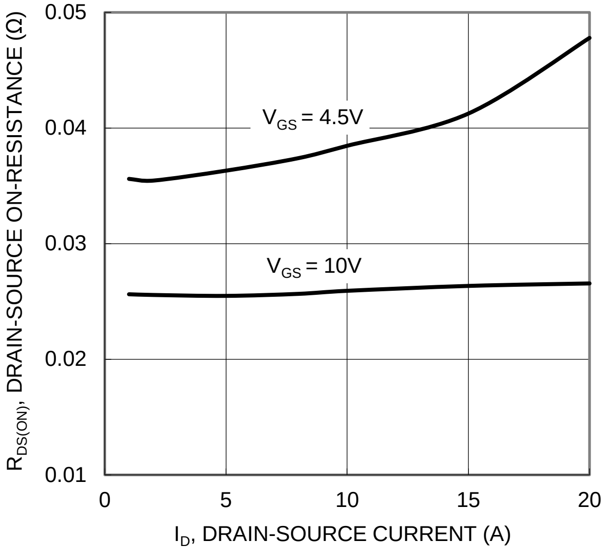


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

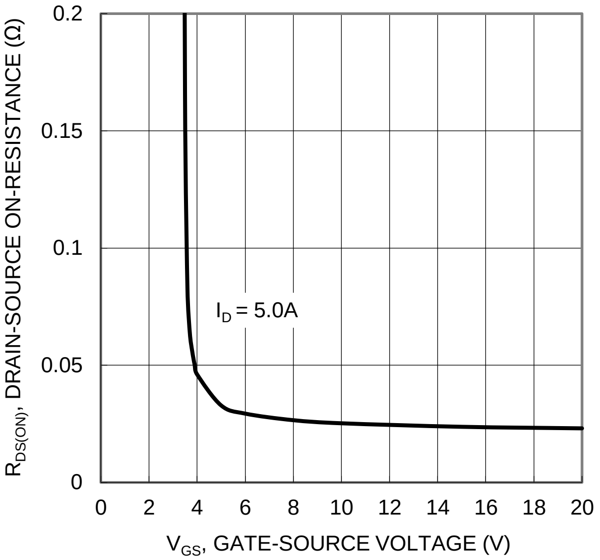


Figure 4. Typical Transfer Characteristic

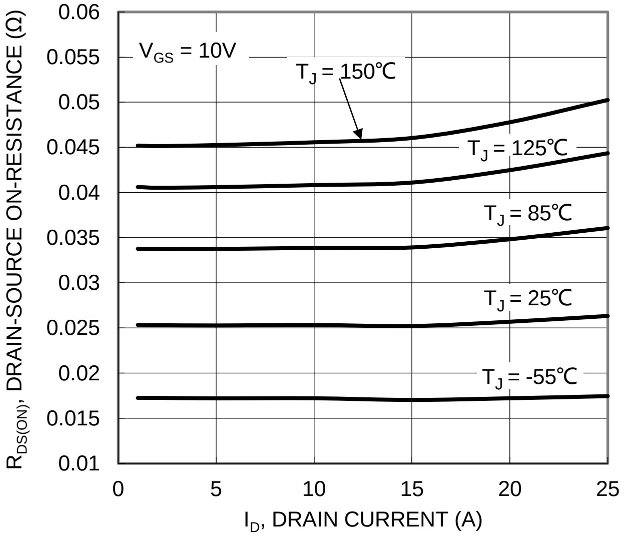


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

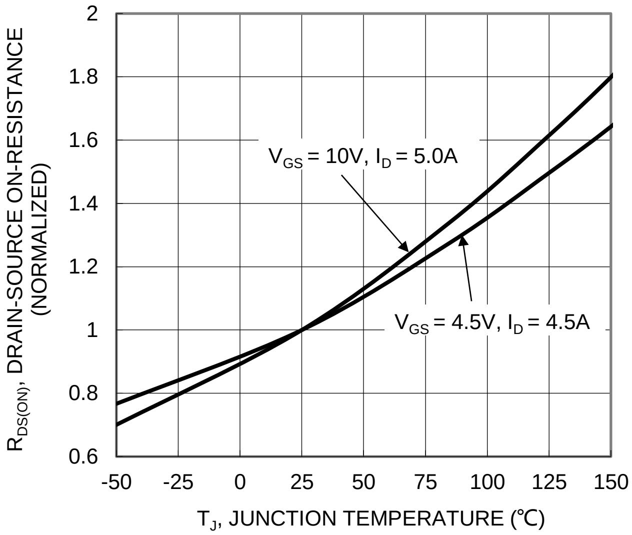


Figure 6. On-Resistance Variation with Temperature

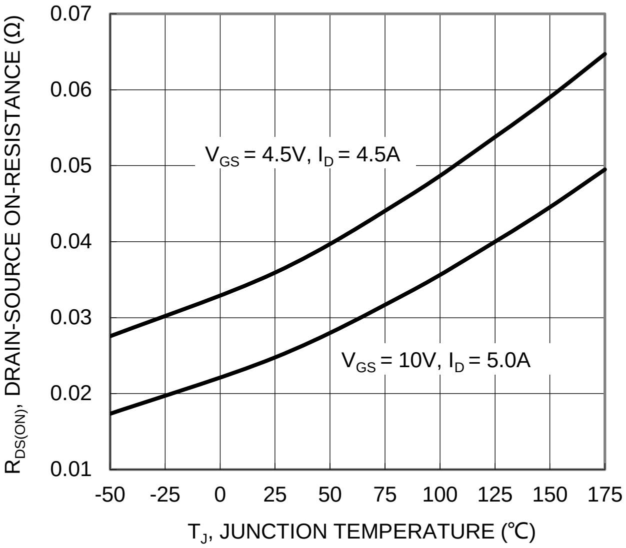


Figure 7. On-Resistance Variation with Temperature

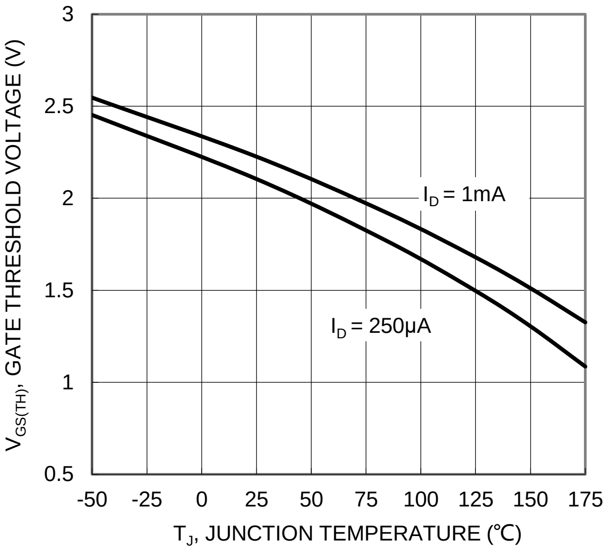


Figure 8. Gate Threshold Variation vs. Junction Temperature

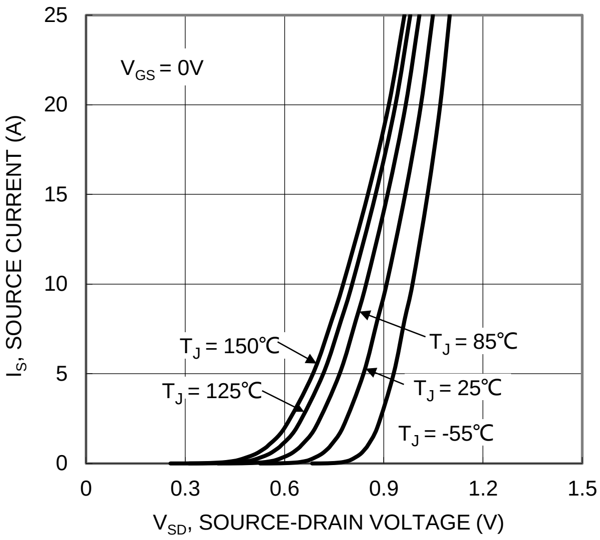


Figure 9. Diode Forward Voltage vs. Current

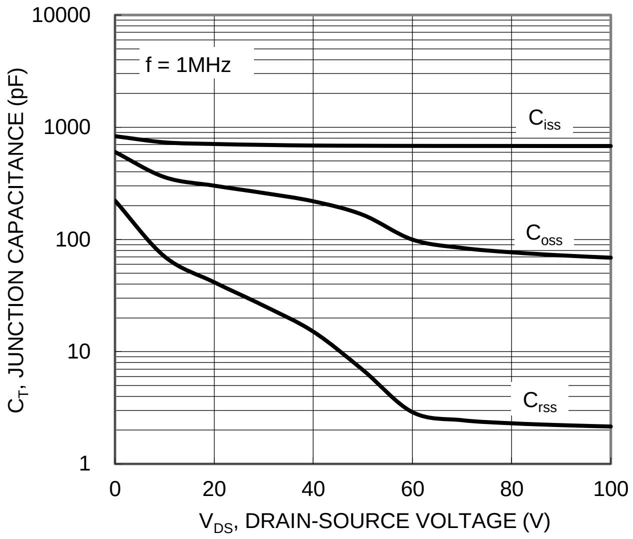


Figure 10. Typical Junction Capacitance

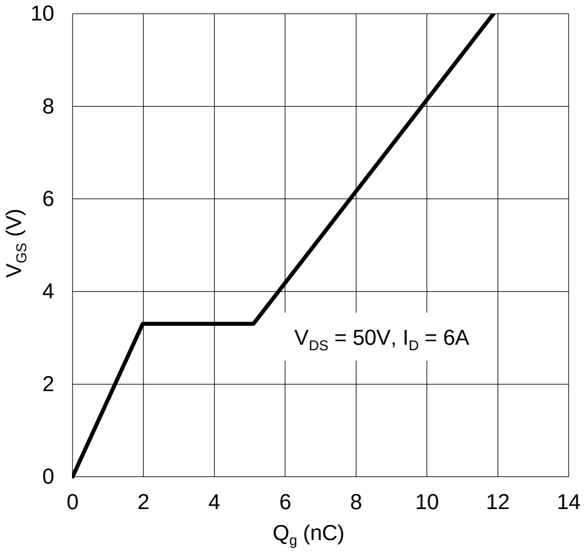


Figure 11. Gate Charge

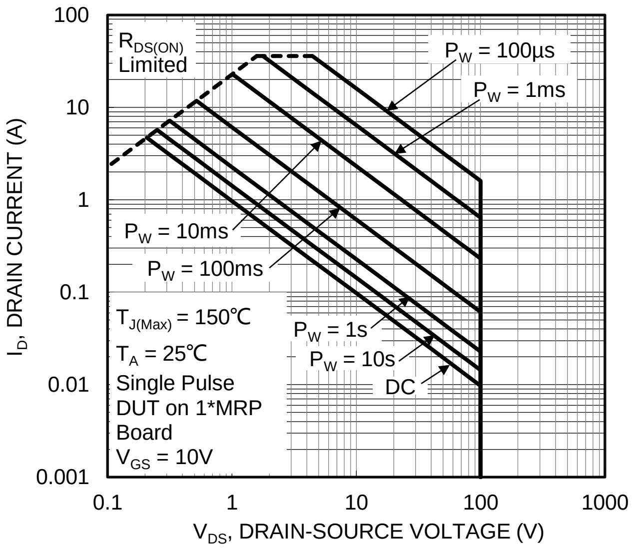


Figure 12. SOA, Safe Operation Area

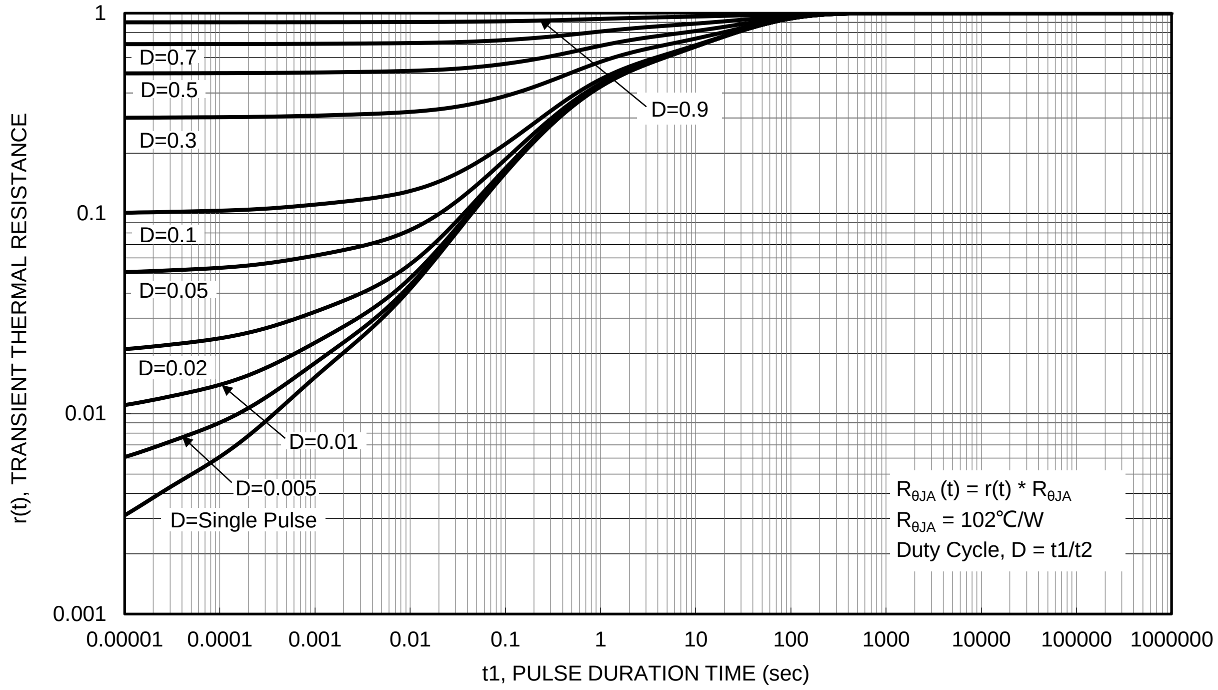
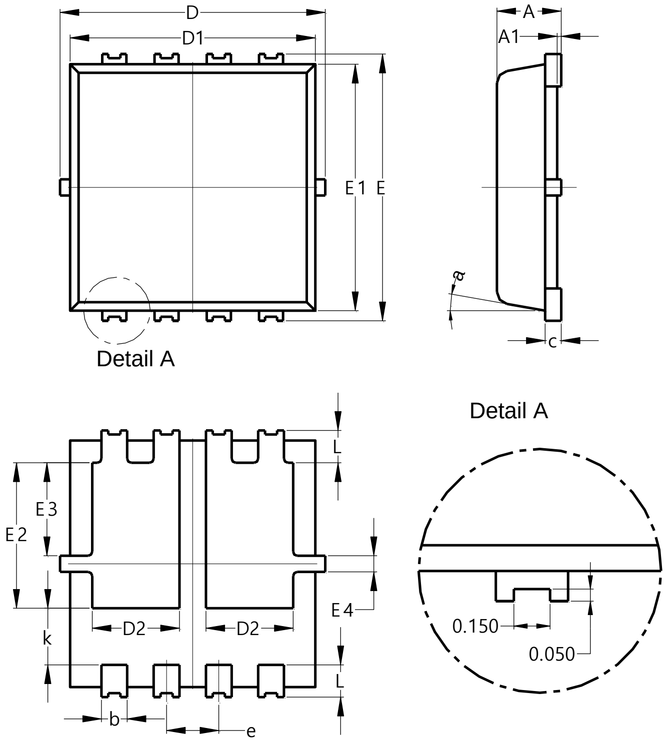


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

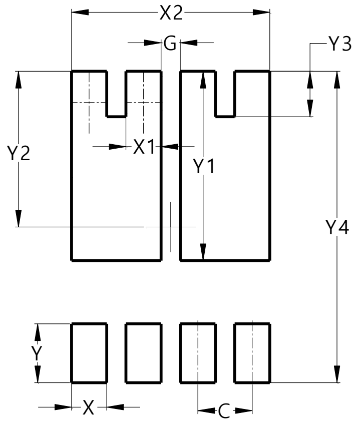
POWERDI®3333-8/SWP (Type UXD)



POWERDI®3333-8/SWP (Type UXD)			
Dim	**Min**	**Max**	**Typ**
A	0.75	0.85	0.80
A1	0.00	0.05	–
b	0.25	0.40	0.32
c	0.10	0.25	0.15
D	3.20	3.40	3.30
D1	2.95	3.15	3.05
D2	1.00	1.20	1.10
E	3.20	3.40	3.30
E1	2.95	3.15	3.05
E2	1.60	2.00	1.80
E3	0.95	1.35	1.15
E4	0.10	0.30	0.20
e	–	–	0.65
L	0.30	0.50	0.40
k	0.50	0.90	0.70
a	0°	12°	10°
All Dimensions in mm			

Suggested Pad Layout

POWERDI®3333-8/SWP (Type UXD)



Dimensions	Value (in mm)
C	0.650
G	0.230
X	0.420
X1	0.420
X2	2.370
Y	0.700
Y1	2.250
Y2	1.850
Y3	0.540
Y4	3.700